

## Description

The AZV831/AZV832 is single/dual channels rail-to-rail input and output amplifier, which provides a wide input common-mode voltage range and output voltage swing capability for maximum signal swings in low supply voltage applications. The device is fully specified to operate from 1.6V to 5.0V single supply, or  $\pm 0.8V$  and  $\pm 2.5V$  dual supply applications. It features very low supply current dissipation 70 $\mu A$  per channel, which is well suitable for today's low-voltage and/or portable systems.

The AZV831/AZV832 features optimal performance in very low bias current of 1pA, which enables the IC to be used for integrators, photodiode amplifiers, and piezoelectric sensors etc. The device has typical 0.5mV input offset voltage and provides 1MHz bandwidth.

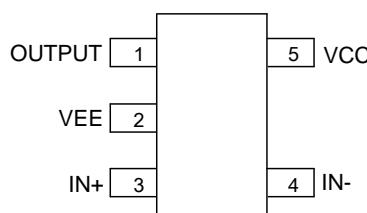
The AZV831/AZV832 adopts the latest packaging technology to meet the most demanding space-constraint applications. The AZV831 is available in standard SOT-23-5 package. The AZV832 is offered in the traditional MSOP-8 and SOIC-8 packages.

## Features

- Single Supply Voltage Range: 1.6V to 5.5V
- Ultra-low Input Bias Current: 1pA (Typ.)
- Offset Voltage: 0.5mV (Typ.), 2.5mV (Max.)
- Rail-to-Rail Input
  - V<sub>CM</sub>: 300mV beyond Rails @ V<sub>CC</sub> = 5V
  - Rail-to-Rail Output Swing:
    - 10k $\Omega$  Load: 4mV from Rail
    - 1k $\Omega$  Load: 25mV from Rail
- Supply Current: 70 $\mu A$ /Amplifier
- Unity Gain Stable
  - Gain Bandwidth Product: 1.0MHz
  - Slew Rate: 0.45V/ $\mu s$  @ V<sub>CC</sub> = 5.0V
- Operation Ambient Temperature Range: -40°C to +85°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

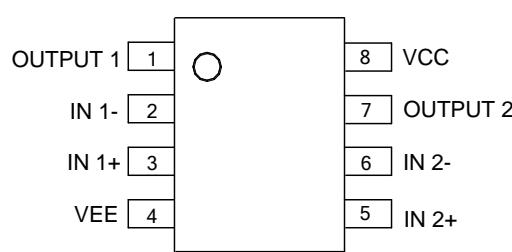
## Pin Assignments

(Top View)



SOT-23-5 (AZV831)

(Top View)



SOIC-8/MSOP-8 (AZV832)

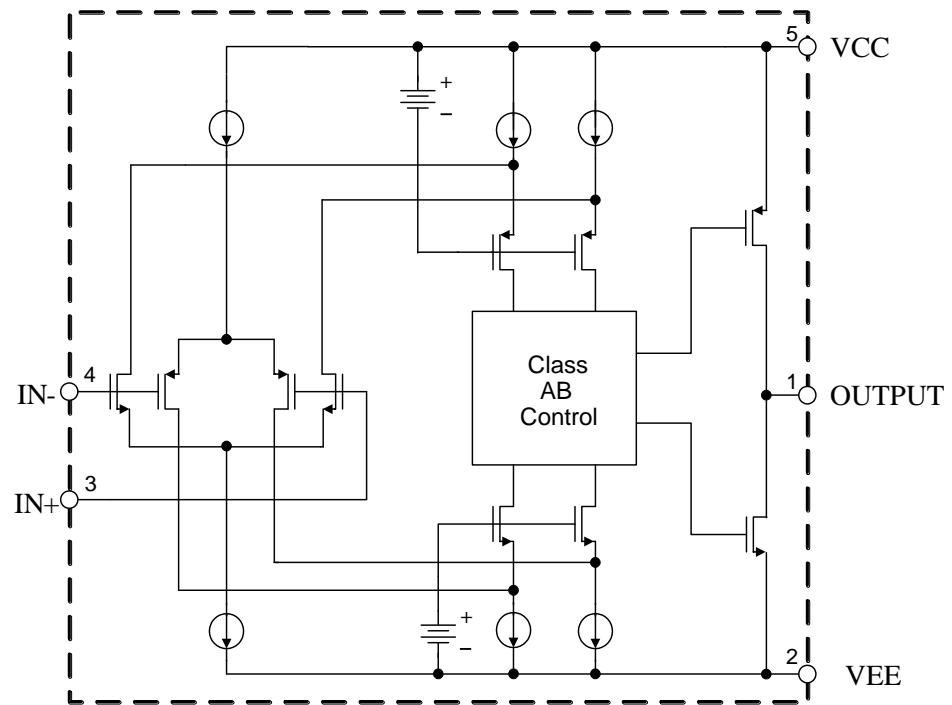
## Applications

- Sensors
- Photodiode Amplification
- Battery-Powered Instrumentation
- Pulse Blood Oximeter, Glucose Meter

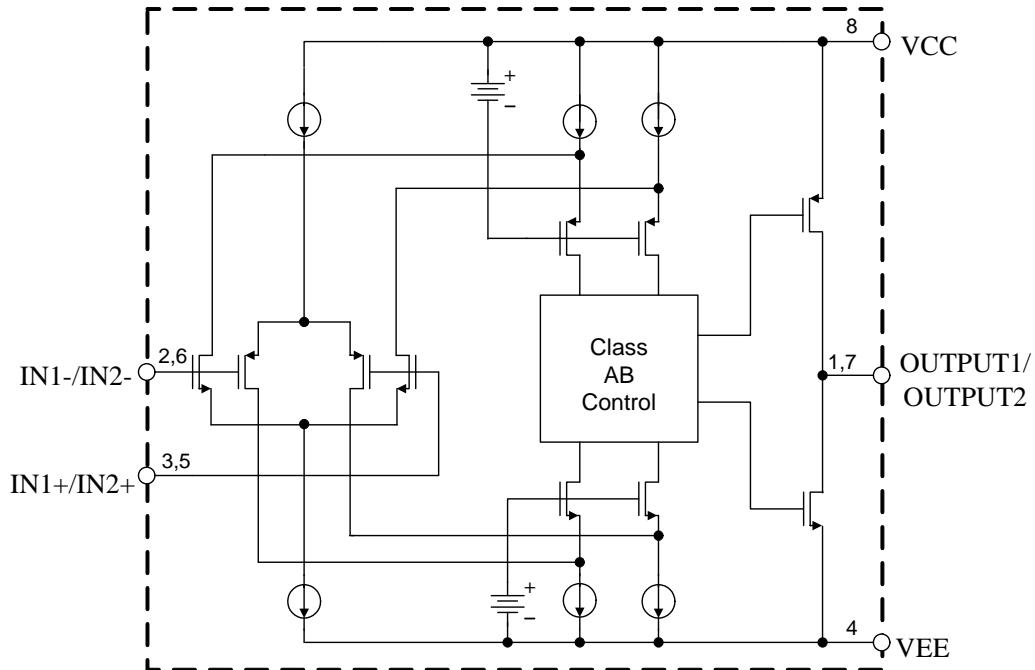
Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Functional Block Diagram



For AZV831



For AZV832/Amplifier

## Absolute Maximum Ratings (Note 4)

Symbol	Parameter	Rating		Unit
$V_{CC}$	Power Supply Voltage	6.0		V
$V_{ID}$	Differential Input Voltage	6.0		V
$V_{IN}$	Input Voltage	-0.3 to $V_{CC}+0.5$		V
$T_J$	Operating Junction Temperature	+150		°C
$\theta_{JA}$	Thermal Resistance (Junction to Ambient)	SOT-23-5	220	°C/W
		SOIC-8	150	
		MSOP-8	200	
$T_{STG}$	Storage Temperature Range	-65 to +150		°C
$T_{LEAD}$	Lead Temperature (Soldering, 10 Seconds)	+260		°C
—	ESD (Human Body Model)	4000		V
—	ESD (Machine Model)	300		V

Note 4: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

## Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	Supply Voltage	1.6	5.5	V
$T_A$	Operating Ambient Temperature Range	-40	+85	°C

## Electrical Characteristics

**1.6V DC Electrical Characteristics** ( $V_{CC} = 1.6V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{OS}$	Input Offset Voltage	—	—	0.5	2.5	mV
$I_B$	Input Bias Current	—	—	1.0	—	pA
$I_{OS}$	Input Offset Current	—	—	1.0	—	pA
$V_{CM}$	Input Common-mode Voltage Range	—	-0.2	—	1.8	V
CMRR	Common-mode Rejection Ratio	$V_{CM} = -0.2V$ to $1.8V$	55	75	—	dB
$G_V$	Large Signal Voltage Gain	$R_L = 10k\Omega$ to $V_{CC}/2$ , $V_{OUT} = 0.2V$ to $1.4V$	90	110	—	dB
$\Delta V_{OS}/\Delta T$	Input Offset Voltage Drift	—	—	2.0	—	$\mu V/^{\circ C}$
$V_{OL}/V_{OH}$	Output Voltage Swing from Rail	$R_L = 1k\Omega$ to $V_{CC}/2$	—	30	50	mV
		$R_L = 10k\Omega$ to $V_{CC}/2$	—	3	15	
$I_{SINK}$	Output Current	Sink	$V_{OUT} = V_{CC}$	8	10	mA
$I_{SOURCE}$		Source	$V_{OUT} = 0V$	5	8.5	
$Z_{OUT}$	Closed-loop Output Impedance	$f = 10kHz$ , $A_V = 1$	—	9	—	$\Omega$
PSRR	Power Supply Rejection Ratio	$V_{CC} = 1.6V$ to $5.0V$	66	80	—	dB
$I_{CC}$	Supply Current (Per Amplifier)	$V_{OUT} = V_{CC}/2$ , $I_{OUT} = 0$	—	70	90	$\mu A$

**1.6V AC Electrical Characteristics** ( $V_{CC} = 1.6V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
GBP	Gain Bandwidth Product	$R_L = 100k\Omega$	—	1.0	—	MHz
SR	Slew Rate (Note 5)	$1V$ Step, $C_L = 100pF$ , $R_L = 10k\Omega$	—	0.32	—	$V/\mu s$
$\Phi_M$	Phase Margin	$R_L = 100k\Omega$	—	67	—	Degrees
THD+N	Total Harmonic Distortion+Noise	$f = 1kHz$ , $A_V = 1$ , $V_{IN} = 1V_{pp}$ $R_L = 10k\Omega$ , $C_L = 100pF$	—	-70	—	dB
$e_n$	Voltage Noise Density	$f = 1kHz$	—	27	—	$nV/\sqrt{Hz}$

Note 5: Number specified is the positive slew rate.

**Electrical Characteristics (Cont.)****1.8V DC Electrical Characteristics** ( $V_{CC} = 1.8V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
$V_{OS}$	Input Offset Voltage		—	—	0.5	2.5	mV
$I_B$	Input Bias Current		—	—	1.0	—	pA
$I_{OS}$	Input Offset Current		—	—	1.0	—	pA
$V_{CM}$	Input Common-mode Voltage Range		—	-0.2	—	2.0	V
CMRR	Common-mode Rejection Ratio		$V_{CM} = -0.2V$ to $2.0V$	55	75	—	dB
$G_V$	Large Signal Voltage Gain		$R_L = 10k\Omega$ to $V_{CC}/2$ , $V_{OUT} = 0.2V$ to $1.6V$	90	112	—	dB
$\Delta V_{OS}/\Delta T$	Input Offset Voltage Drift		—	—	2.0	—	$\mu V/^{\circ}C$
$V_{OL}/V_{OH}$	Output Voltage Swing from Rail		$R_L = 1k\Omega$ to $V_{CC}/2$	—	25	50	mV
			$R_L = 10k\Omega$ to $V_{CC}/2$	—	3	15	
$I_{SINK}$	Output Current	Sink	$V_{OUT} = V_{CC}$	12	16	—	mA
$I_{SOURCE}$		Source	$V_{OUT} = 0V$	10	14	—	
$Z_{OUT}$	Closed-loop Output Impedance		$f = 10kHz$	—	9	—	$\Omega$
PSRR	Power Supply Rejection Ratio		$V_{CC} = 1.6V$ to $5.0V$	66	80	—	dB
$I_{CC}$	Supply Current (Per Amplifier)		$V_{OUT} = V_{CC}/2$ , $I_{OUT} = 0$	—	70	90	$\mu A$

**1.8V AC Electrical Characteristics** ( $V_{CC} = 1.8V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
GBP	Gain Bandwidth Product		$R_L = 100k\Omega$	—	1.0	—	MHz
SR	Slew Rate (Note 5)		1V Step, $C_L = 100pF$ , $R_L = 10k\Omega$	—	0.34	—	V/ $\mu$ s
$\phi_M$	Phase Margin		$R_L = 100k\Omega$	—	67	—	Degrees
THD+N	Total Harmonic Distortion+Noise		$f = 1kHz$ , $A_V = 1$ , $V_{IN} = 1V_{pp}$ $R_L = 10k\Omega$ , $C_L = 100pF$	—	-70	—	dB
$e_n$	Voltage Noise Density		$f = 1kHz$	—	27	—	$nV/\sqrt{Hz}$

Note 5: Number specified is the positive slew rate.

**Electrical Characteristics (Cont.)**
**3.0V DC Electrical Characteristics** ( $V_{CC} = 3.0V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
$V_{OS}$	Input Offset Voltage		—	—	0.5	2.5	mV
$I_B$	Input Bias Current		—	—	1.0	—	pA
$I_{OS}$	Input Offset Current		—	—	1.0	—	pA
$V_{CM}$	Input Common-mode Voltage Range		—	-0.3	—	3.3	V
CMRR	Common-mode Rejection Ratio		$V_{CM} = -0.3V$ to $1.8V$	62	80	—	dB
			$V_{CM} = -0.3V$ to $3.3V$	58	75	—	
$G_V$	Large Signal Voltage Gain		$R_L = 1k\Omega$ to $V_{CC}/2$ , $V_{OUT} = 0.2V$ to $2.8V$	90	110	—	dB
			$R_L = 10k\Omega$ to $V_{CC}/2$ , $V_{OUT} = 0.1V$ to $2.9V$	95	115	—	
$\Delta V_{OS}/\Delta T$	Input Offset Voltage Drift		—	—	2.0	—	$\mu V/\text{ }^\circ C$
$V_{OL}/V_{OH}$	Output Voltage Swing from Rail		$R_L = 1k\Omega$ to $V_{CC}/2$	—	20	50	mV
			$R_L = 10k\Omega$ to $V_{CC}/2$	—	3	15	
$I_{SINK}$	Output Current	Sink	$V_{OUT} = V_{CC}$	50	60	—	mA
$I_{SOURCE}$		Source	$V_{OUT} = 0V$	50	65	—	
$Z_{OUT}$	Closed-loop Output Impedance		$f = 10\text{kHz}$	—	9	—	$\Omega$
PSRR	Power Supply Rejection Ratio		$V_{CC} = 1.6V$ to $5.0V$	66	80	—	dB
$I_{CC}$	Supply Current (Per Amplifier)		$V_{OUT} = V_{CC}/2$ , $I_{OUT} = 0$	—	70	90	$\mu A$

**3.0V AC Electrical Characteristics** ( $V_{CC} = 3.0V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
GBP	Gain Bandwidth Product		$R_L = 100k\Omega$	—	1.0	—	MHz
SR	Slew Rate (Note 5)		$G = 1$ , $2V$ Step, $C_L = 100pF$ , $R_L = 10k\Omega$	—	0.40	—	$V/\mu s$
$\Phi_M$	Phase Margin		$R_L = 100k\Omega$	—	67	—	Degrees
THD+N	Total Harmonic Distortion+Noise		$f = 1\text{kHz}$ , $G = 1$ , $V_{IN} = 1V_{pp}$ $R_L = 10k\Omega$ , $C_L = 100pF$	—	-70	—	dB
$e_n$	Voltage Noise Density		$f = 1\text{kHz}$	—	27	—	$nV/\sqrt{Hz}$

Note 5: Number specified is the positive slew rate.

**Electrical Characteristics (Cont.)**
**5.0V DC Electrical Characteristics** ( $V_{CC} = 5.0V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
$V_{OS}$	Input Offset Voltage		—	—	0.5	2.5	mV
$I_B$	Input Bias Current		—	—	1.0	—	pA
$I_{OS}$	Input Offset Current		—	—	1.0	—	pA
$V_{CM}$	Input Common-mode Voltage Range		—	-0.3	—	5.3	V
CMRR	Common-mode Rejection Ratio		$V_{CM} = -0.3V$ to $3.8V$	70	85	—	dB
			$V_{CM} = -0.3V$ to $5.3V$	65	90	—	
$G_V$	Large Signal Voltage Gain		$R_L = 1k\Omega$ to $V_{CC}/2$ , $V_{OUT} = 0.2V$ to $4.8V$	80	92	—	dB
			$R_L = 10k\Omega$ to $V_{CC}/2$ , $V_{OUT} = 0.05V$ to $4.95V$	85	98	—	
$\Delta V_{OS}/\Delta T$	Input Offset Voltage Drift		—	—	2.0	—	$\mu V/^\circ C$
$V_{OL}/V_{OH}$	Output Voltage Swing from Rail		$R_L = 1k\Omega$ to $V_{CC}/2$	—	25	50	mV
			$R_L = 10k\Omega$ to $V_{CC}/2$	—	4	15	
$I_{SINK}$	Output Current	Sink	$V_{OUT} = V_{CC}$	100	150	—	mA
$I_{SOURCE}$		Source	$V_{OUT} = 0V$	110	185	—	
—	Closed-loop Output Impedance		$f = 1kHz$ , $A_V = 1$	—	9	—	$\Omega$
PSRR	Power Supply Rejection Ratio		$V_{CC} = 1.6V$ to $5.0V$	66	80	—	dB
$I_{CC}$	Supply Current (Per Amplifier)		$V_{OUT} = V_{CC}/2$ , $I_{OUT} = 0$	—	70	90	$\mu A$

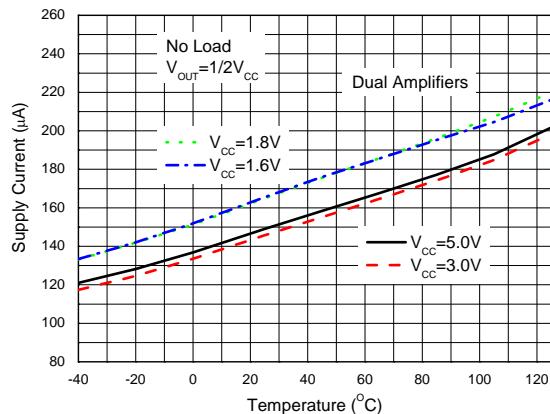
**5.0V AC Electrical Characteristics** ( $V_{CC} = 5.0V$ ,  $V_{EE} = 0$ ,  $V_{OUT} = V_{CC}/2$ ,  $V_{CM} = V_{CC}/2$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

Symbol	Parameter		Conditions	Min	Typ	Max	Unit
GBP	Gain Bandwidth Product		$R_L = 100k\Omega$	—	1.0	—	MHz
SR	Slew Rate (Note 5)		$2V$ Step, $C_L = 100pF$ , $R_L = 10k\Omega$	—	0.45	—	$V/\mu s$
$\phi_M$	Phase Margin		$R_L = 100k\Omega$	—	67	—	Degrees
THD+N	THD+N		$f = 1kHz$ , $A_V = 1$ , $V_{IN} = 1V_{PP}$ $R_L = 10k\Omega$ , $C_L = 100pF$	—	-70	—	dB
$e_n$	Voltage Noise Density		$f = 1kHz$	—	27	—	$nV/\sqrt{Hz}$

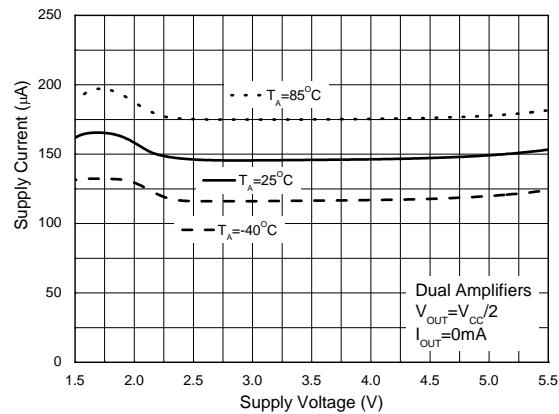
Note 5: Number specified is the positive slew rate.

## Performance Characteristics

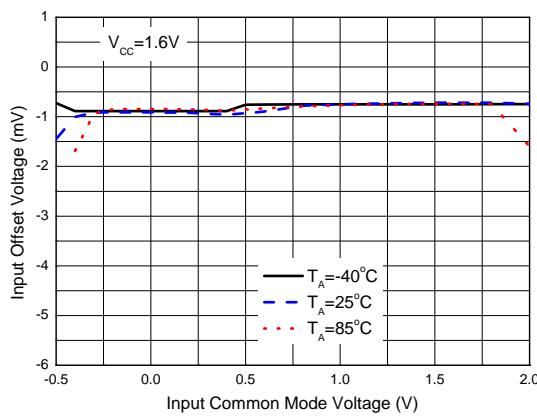
Supply Current vs. Temperature



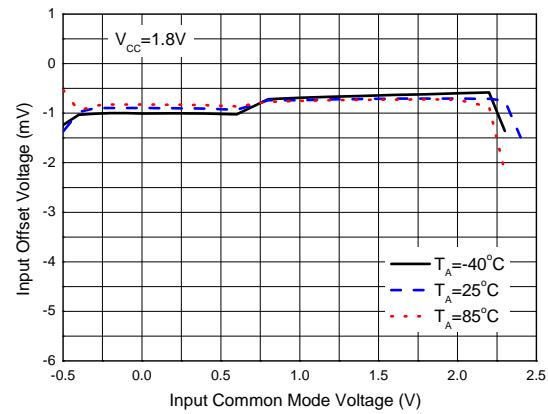
Supply Current vs. Supply Voltage



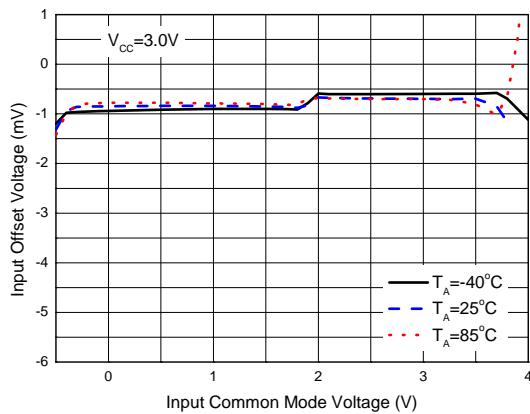
Input Offset Voltage vs.  
Input Common Mode Voltage



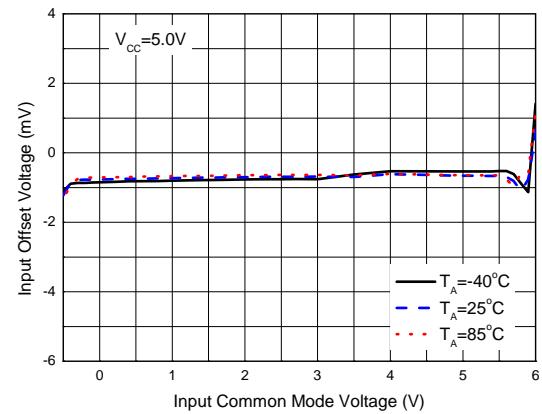
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Input Offset Voltage vs.  
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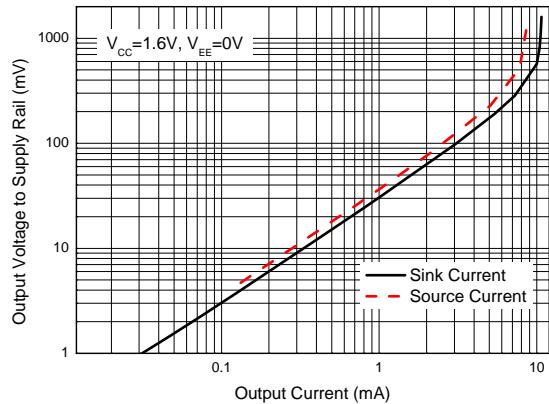


Input Offset Voltage vs.  
Input Common Mode Voltage

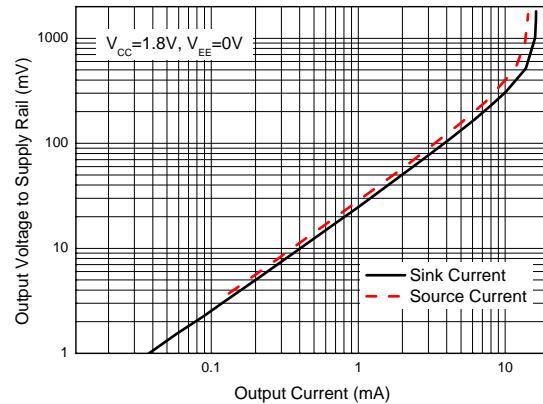


## Performance Characteristics (Cont.)

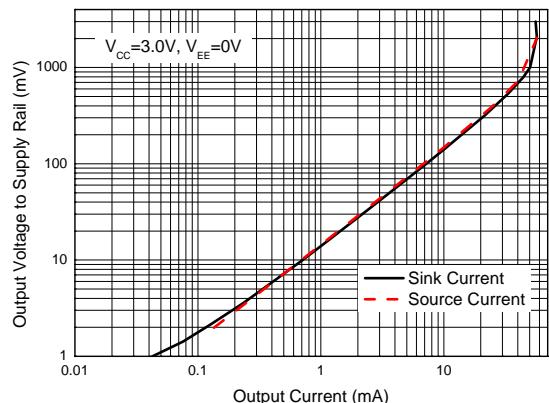
Output Voltage vs. Output Current



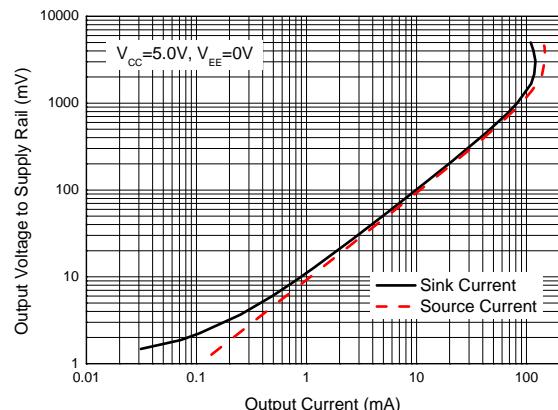
Output Voltage vs. Output Current



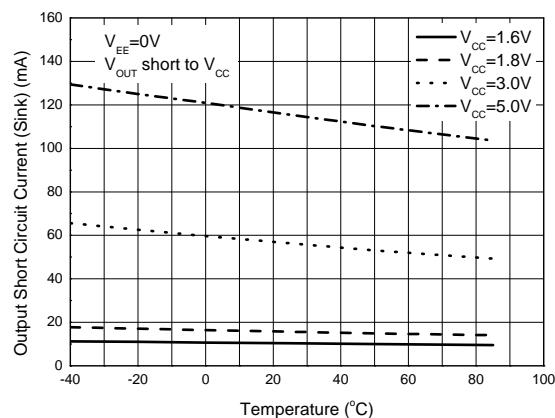
Output Voltage vs. Output Current



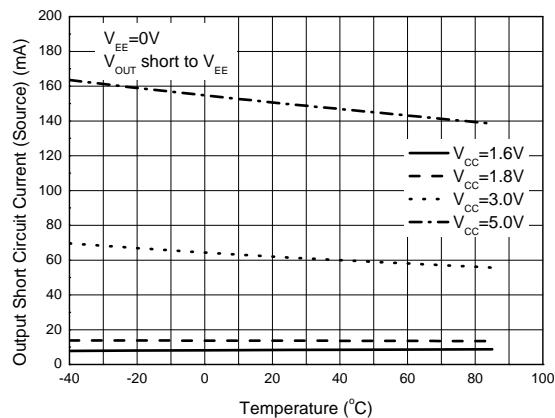
Output Voltage vs. Output Current



Output Short Circuit Current vs. Temperature

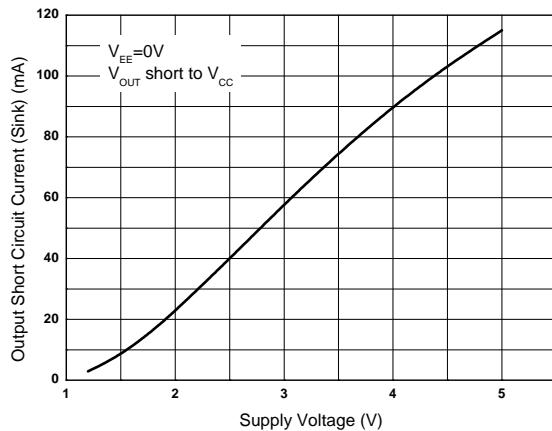


Output Short Circuit Current vs. Temperature

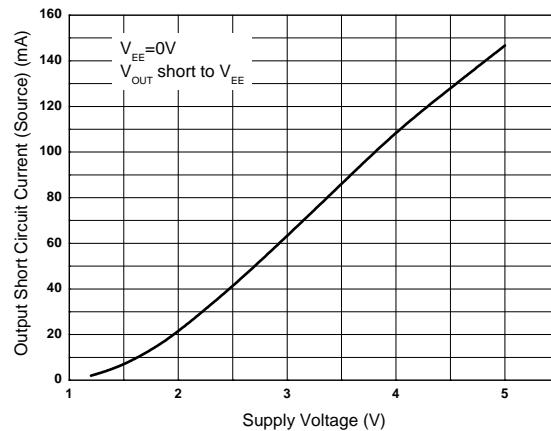


## Performance Characteristics (Cont.)

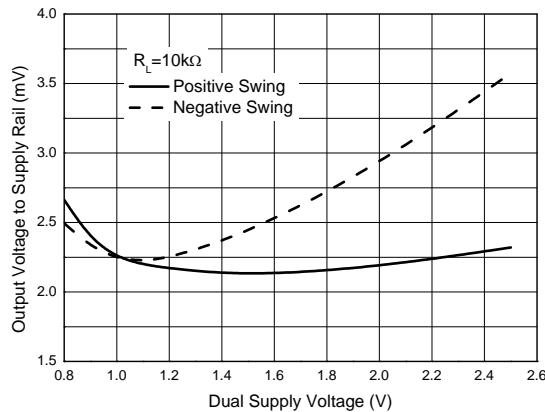
**Output Short Circuit Current  
vs. Supply Voltage**



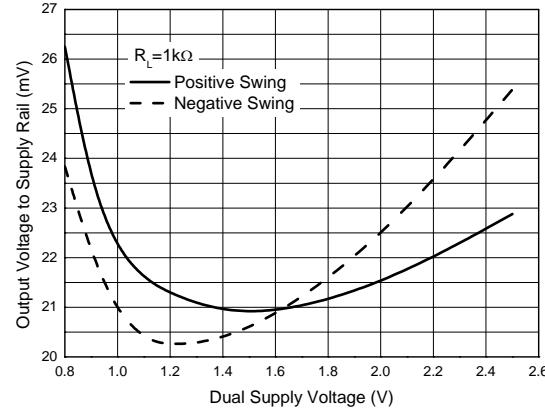
**Output Short Circuit Current  
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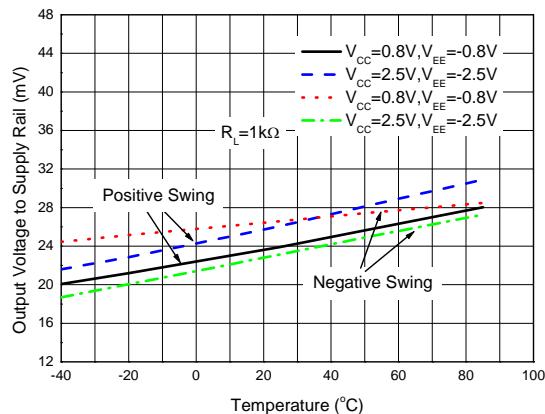
**Output Voltage Swing vs. Supply Voltage**



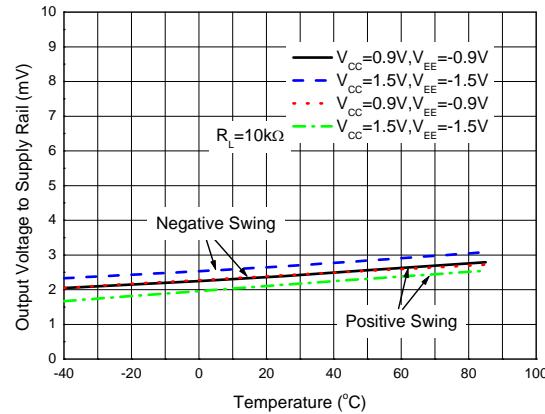
**Output Voltage Swing vs. Supply Voltage**



**Output Voltage Swing vs. Temperature**

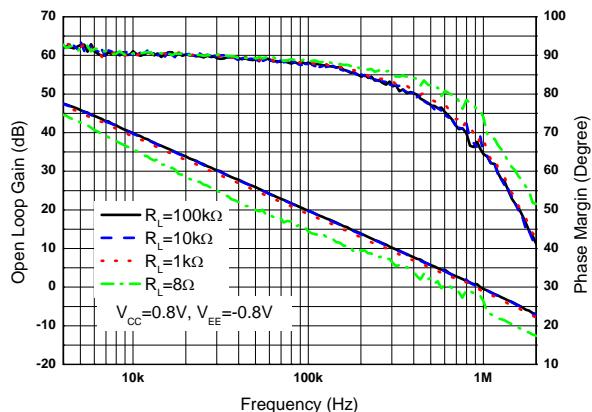


**Output Voltage Swing vs. Temperature**

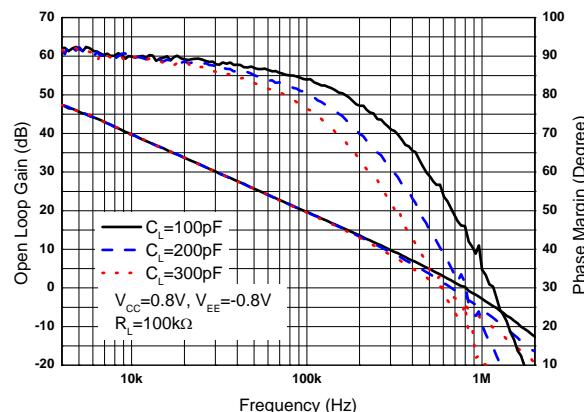


## Performance Characteristics (Cont.)

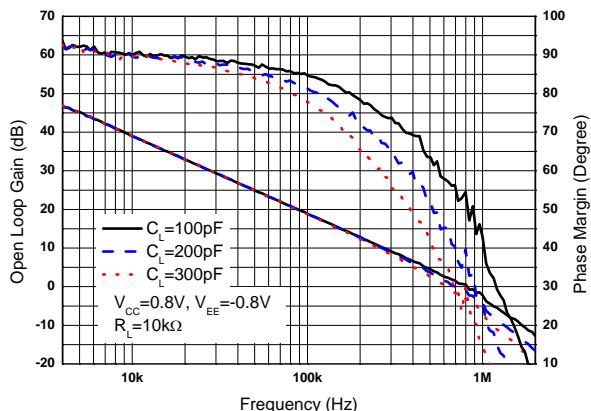
**Gain and Phase vs. Frequency  
with Resistive Load**



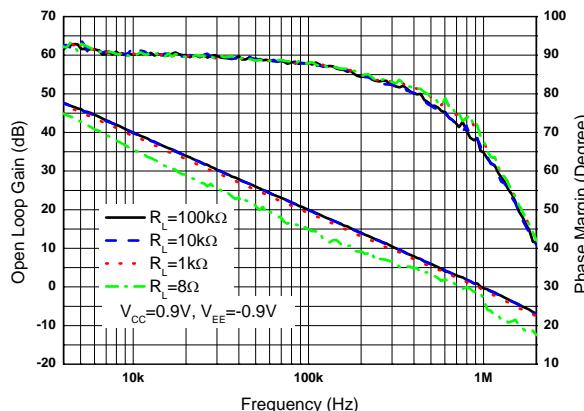
**Gain and Phase vs. Frequency  
with Capacitive Load**



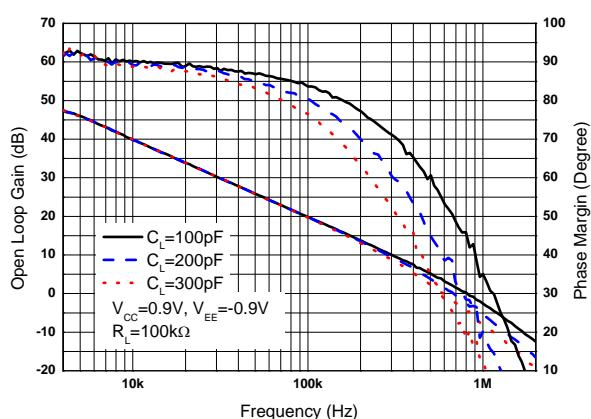
**Gain and Phase vs. Frequency  
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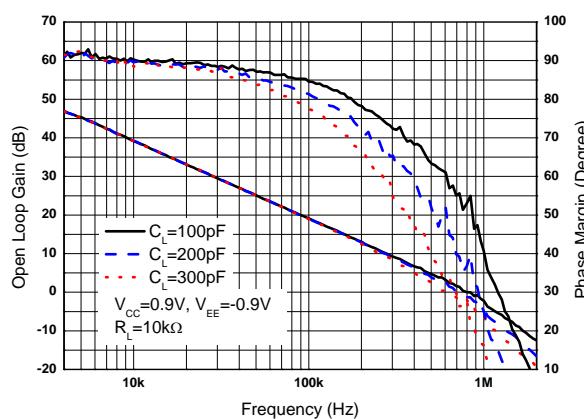
**Gain and Phase vs. Frequency  
with Resistive Load**



**Gain and Phase vs. Frequency  
with Capacitive Load**

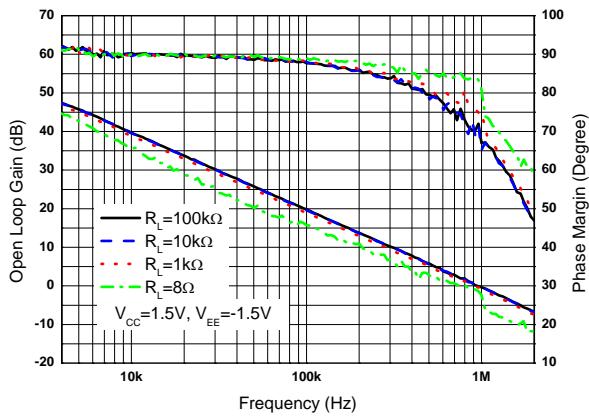


**Gain and Phase vs. Frequency  
with Capacitive Load**

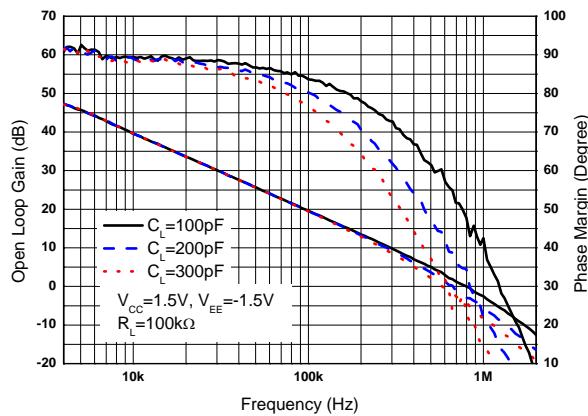


## Performance Characteristics (Cont.)

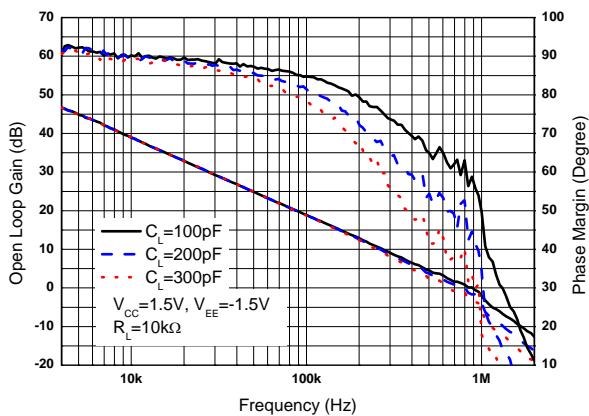
**Gain and Phase vs. Frequency  
with Resistive Load**



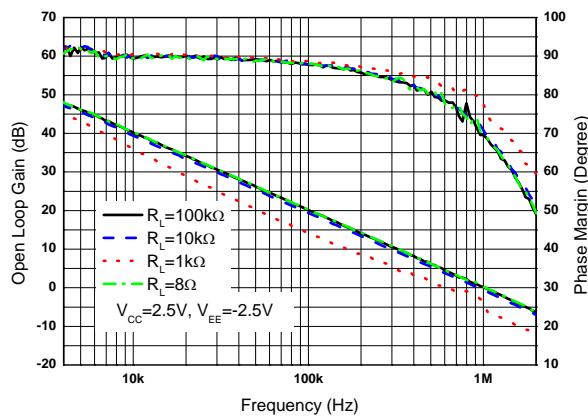
**Gain and Phase vs. Frequency  
with Capacitive Load**



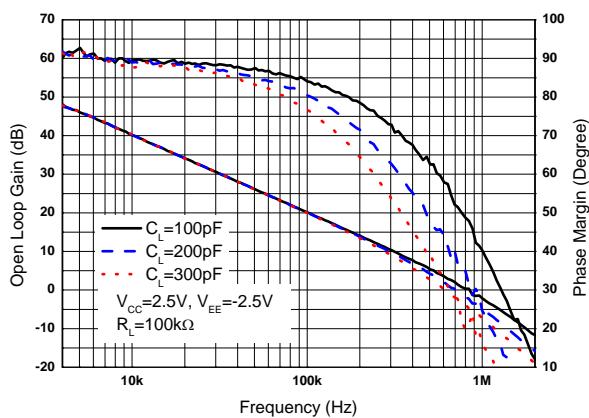
**Gain and Phase vs. Frequency  
with Capacitive Load**



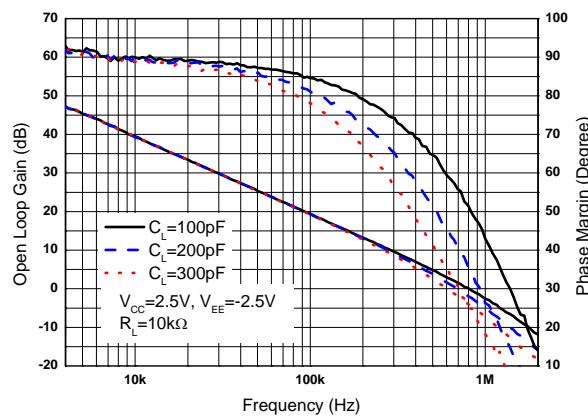
**Gain and Phase vs. Frequency  
with Resistive Load**



**Gain and Phase vs. Frequency  
with Capacitive Load**

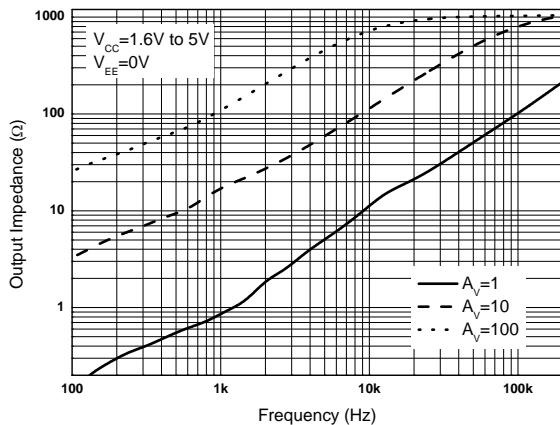


**Gain and Phase vs. Frequency  
with Capacitive Load**

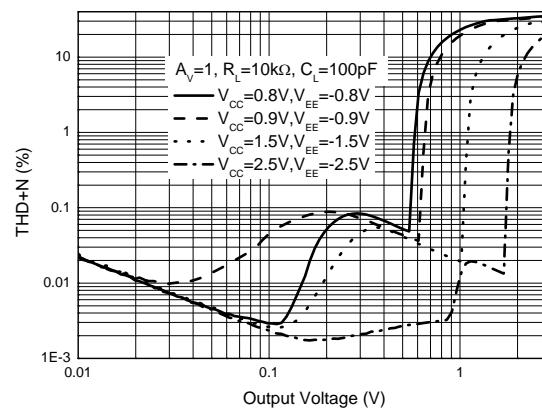


## Performance Characteristics (Cont.)

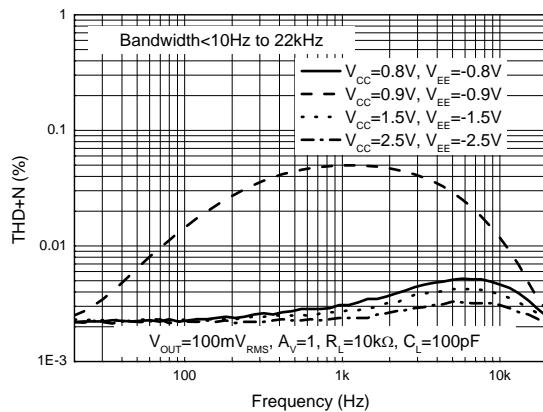
### Output Impedance vs. Frequency



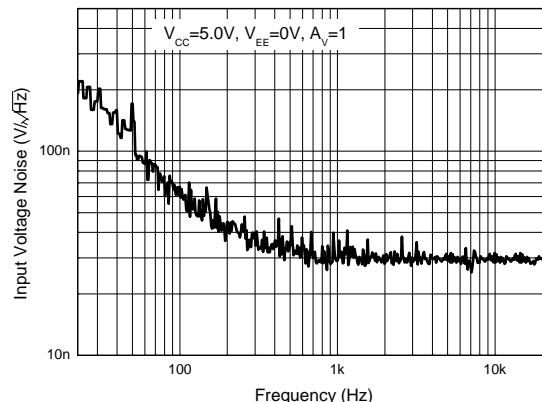
### THD+N vs. Output Voltage



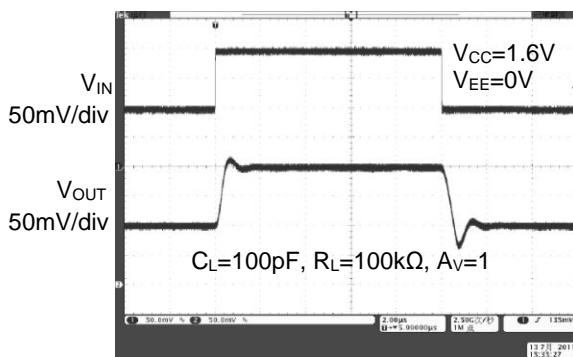
### THD+N vs. Frequency



### Input Voltage Noise Density

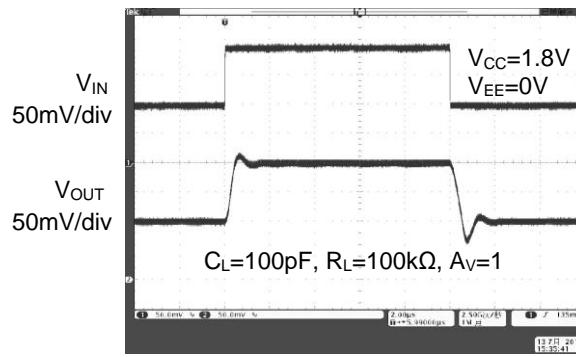


### Small Signal Pulse Response



Time (2 $\mu$ s/div)

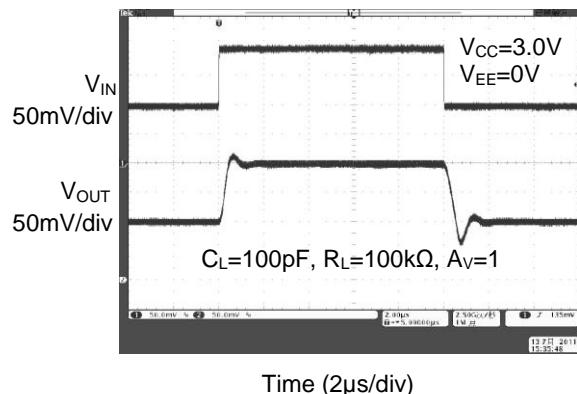
### Small Signal Pulse Response



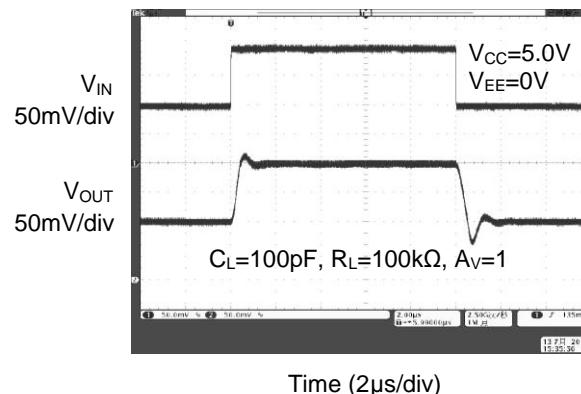
Time (2 $\mu$ s/div)

## Performance Characteristics (Cont.)

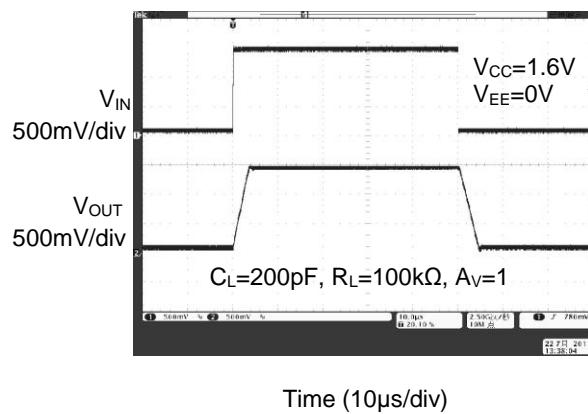
**Small Signal Pulse Response**



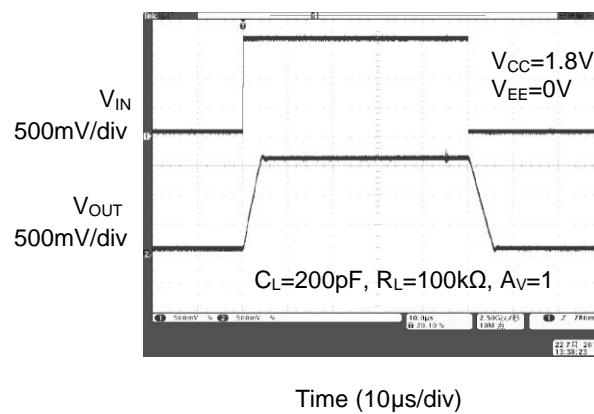
**Small Signal Pulse Response**



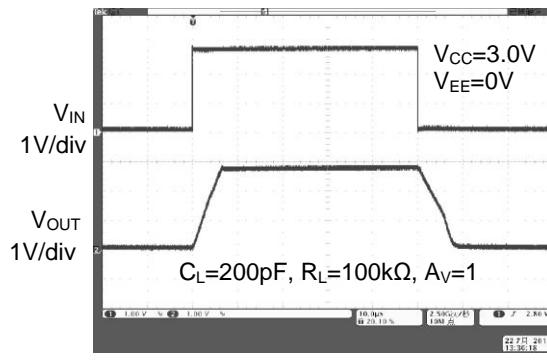
**Large Signal Pulse Response**



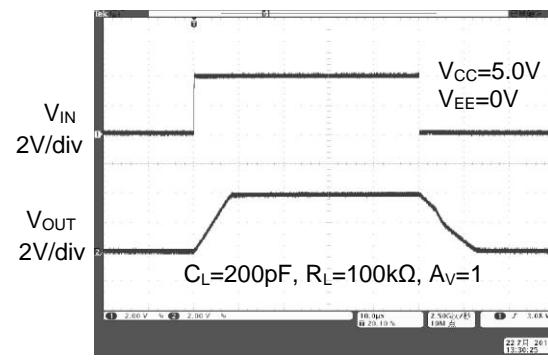
**Large Signal Pulse Response**



**Large Signal Pulse Response**

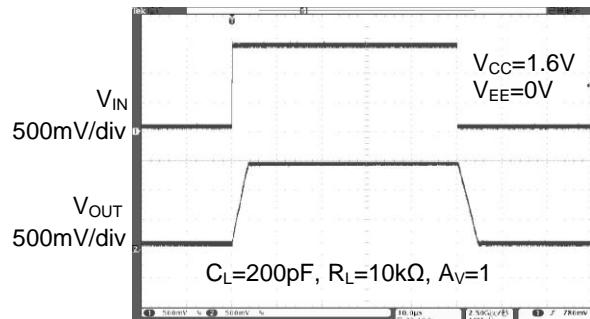


**Large Signal Pulse Response**



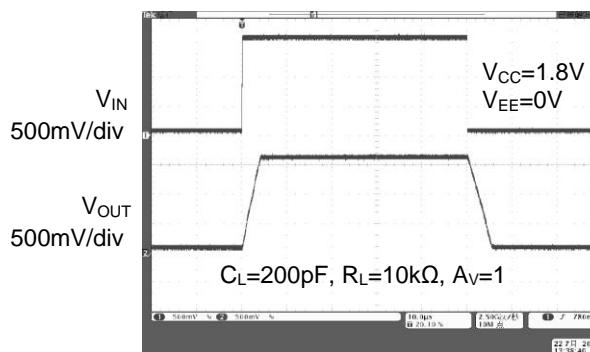
## Performance Characteristics (Cont.)

### Large Signal Pulse Response



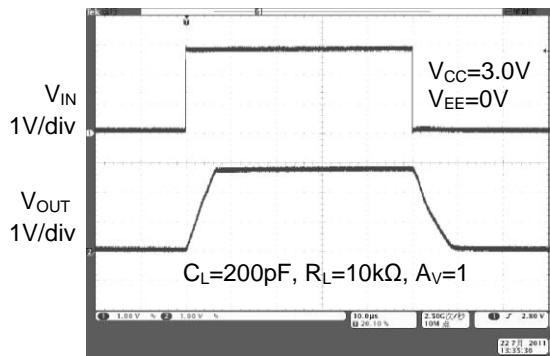
Time (10μs/div)

### Large Signal Pulse Response



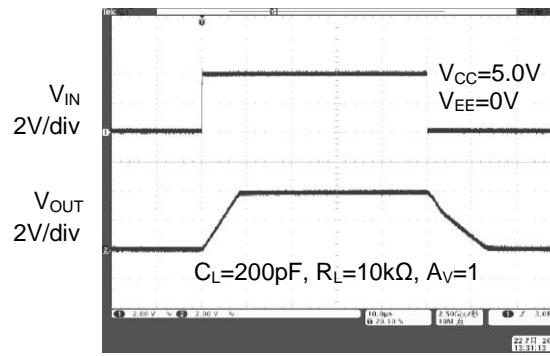
Time (10μs/div)

### Large Signal Pulse Response



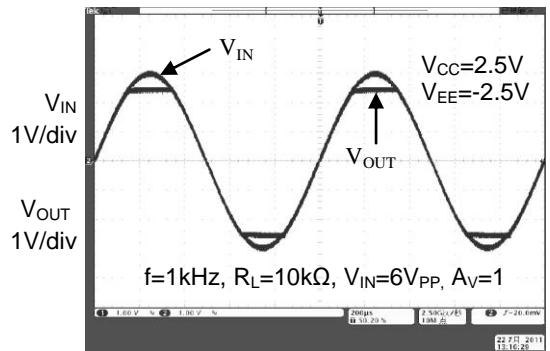
Time (10μs/div)

### Large Signal Pulse Response



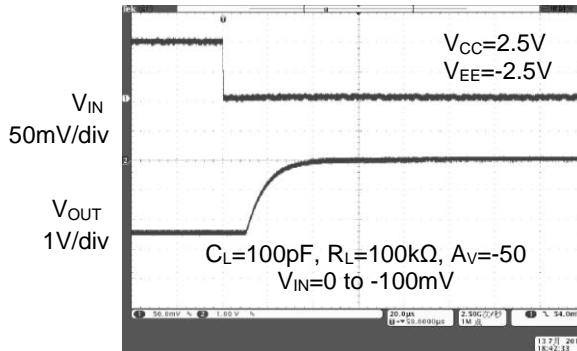
Time (10μs/div)

### No Phase Reversal

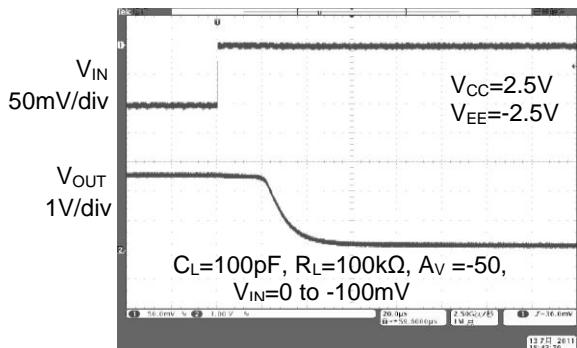


Time (200μs/div)

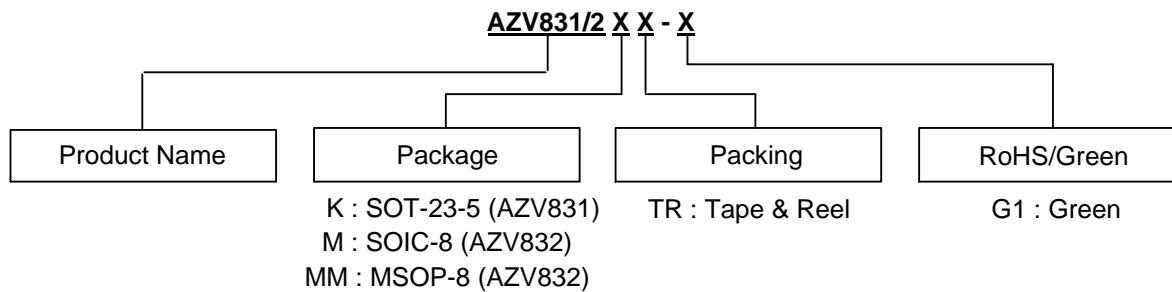
### Overload Recovery Time



Time (20μs/div)

**Performance Characteristics (Cont.)****Overload Recovery Time**Time (20 $\mu$ s/div)

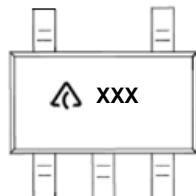
## Ordering Information



Package	Temperature Range	Part Number	Marking ID	Packing
SOT-23-5	-40 to +85°C	AZV831KTR-G1	G4D	3000/7" Tape & Reel
SOIC-8	-40 to +85°C	AZV832MTR-G1	832M-G1	4000/13" Tape & Reel
MSOP-8	-40 to +85°C	AZV832MMTR-G1	832MM-G1	4000/13" Tape & Reel

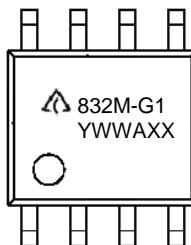
## Marking Information

### (1) SOT-23-5



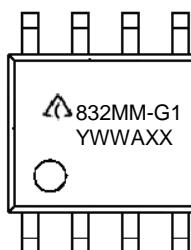
: Logo  
**XXX:** Marking ID (See Ordering Information)

### (2) SOIC-8



First Lines: Logo and Marking ID (See Ordering Information)  
Second Line: Date Code  
Y: Year  
WW: Work Week of Molding  
A: Assembly House Code  
XX: 7<sup>th</sup> and 8<sup>th</sup> Digits of Batch Number

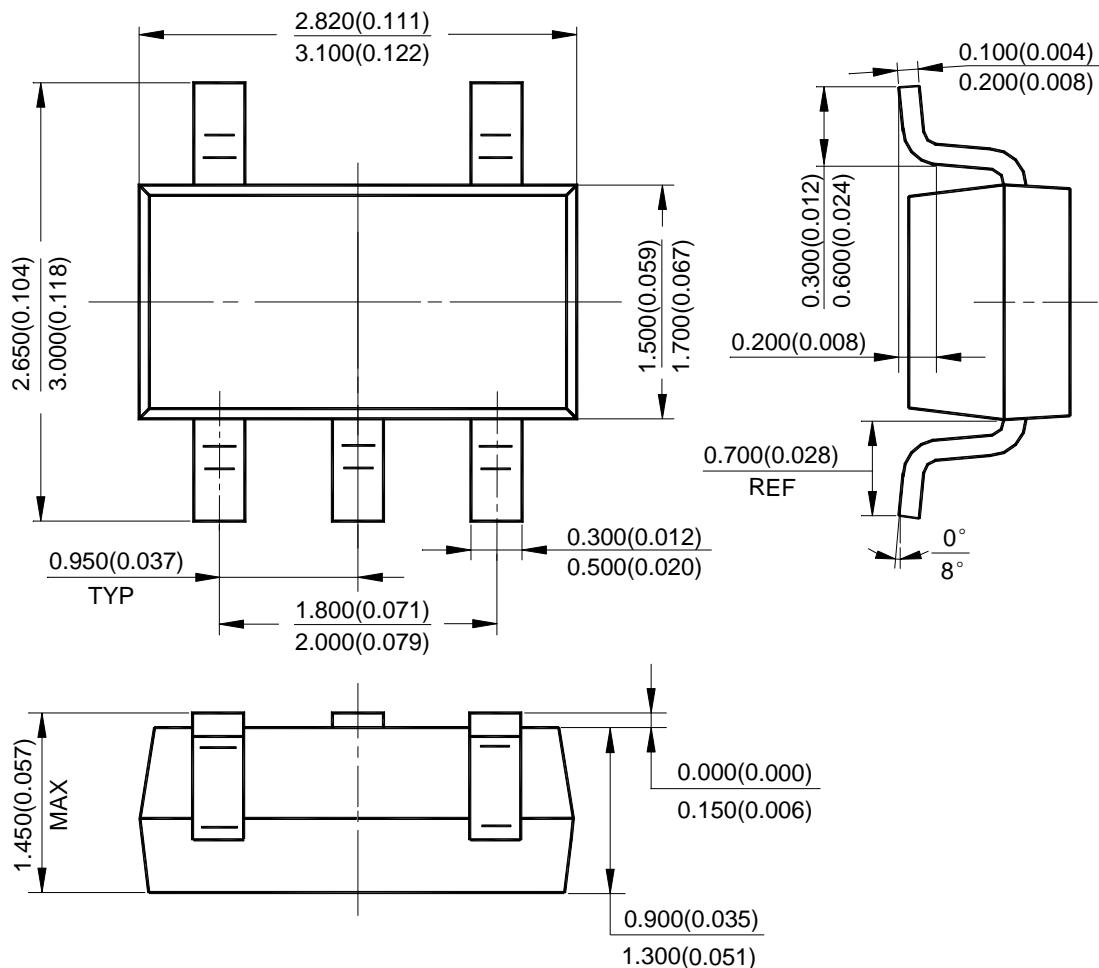
### (3) MSOP-8



First Lines: Logo and Marking ID (See Ordering Information)  
Second Line: Date Code  
Y: Year  
WW: Work Week of Molding  
A: Assembly House Code  
XX: 7<sup>th</sup> and 8<sup>th</sup> Digits of Batch Number

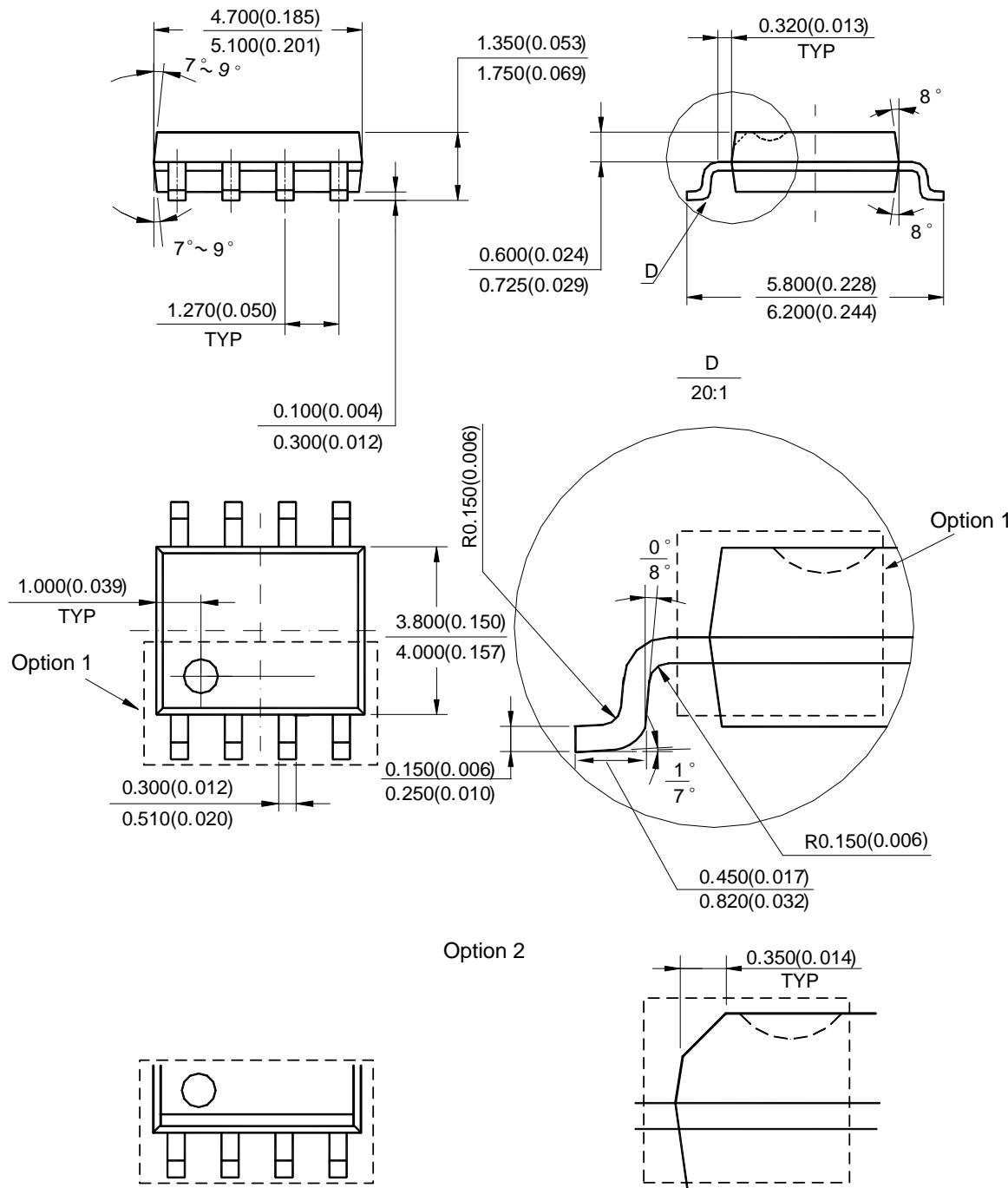
## Package Outline Dimensions (All dimensions in mm(inch).)

(1) Package Type: SOT-23-5



## Package Outline Dimensions (Cont. All dimensions in mm(inch).)

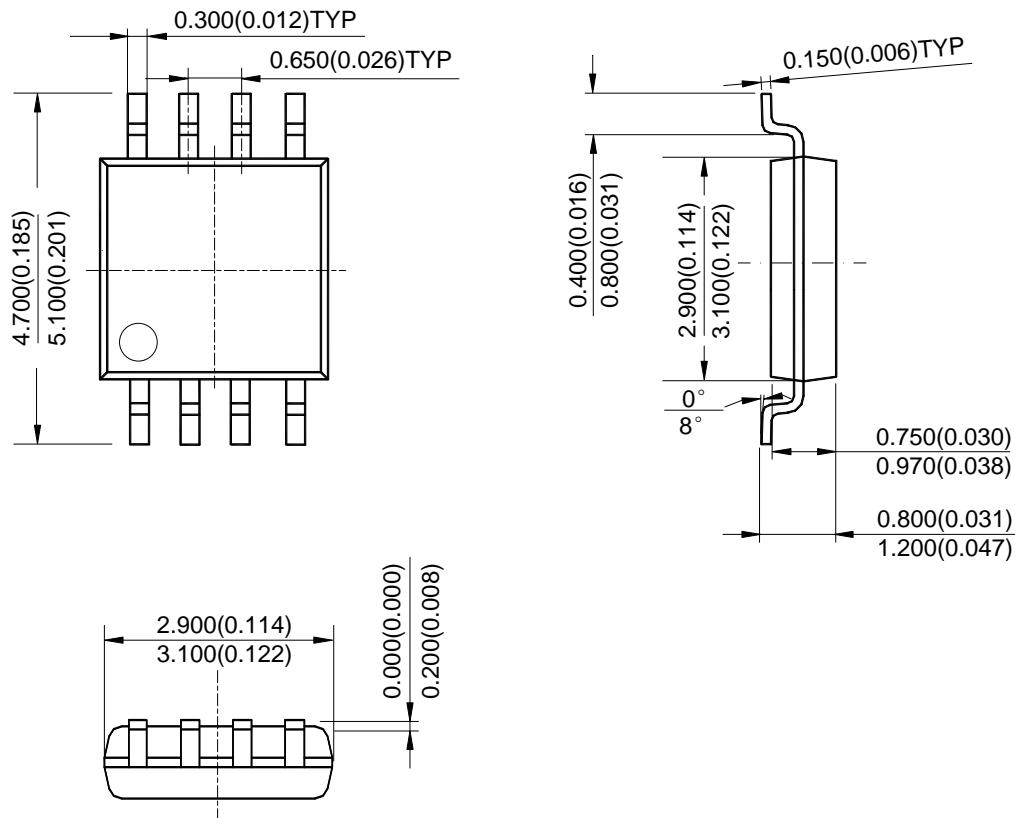
### (2) Package Type: SOIC-8



Note: Eject hole, oriented hole and mold mark is optional.

## Package Outline Dimensions (Cont. All dimensions in mm(inch).)

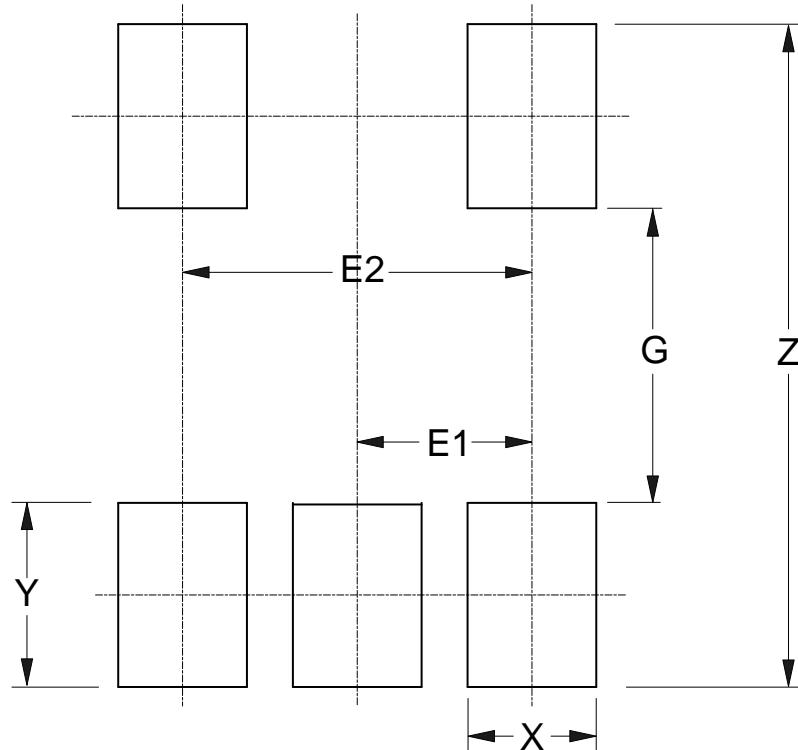
### (3) Package Type: MSOP-8



Note: Eject hole, oriented hole and mold mark is optional.

## Suggested Pad Layout

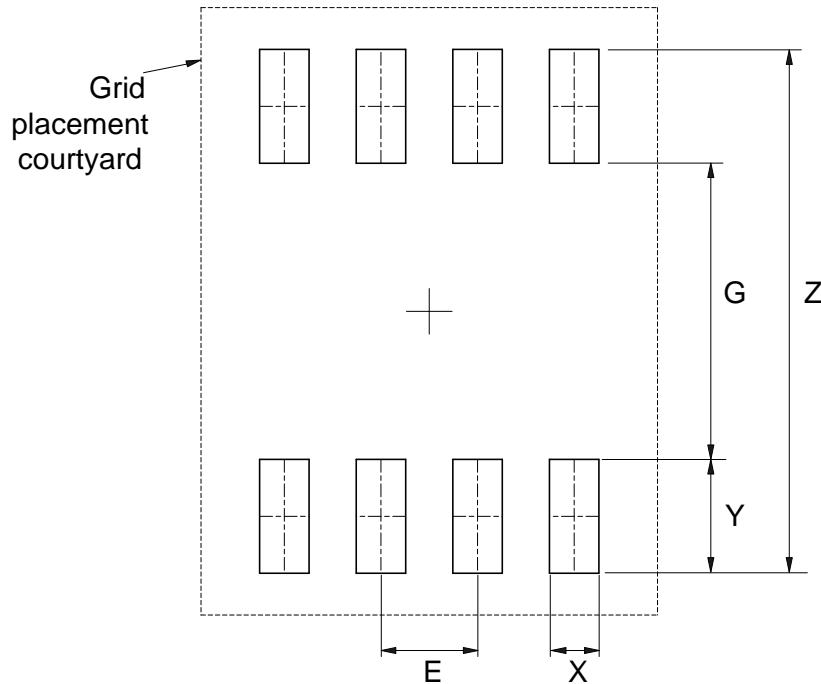
(1) Package Type: SOT-23-5



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E1 (mm)/(inch)	E2 (mm)/(inch)
Value	3.600/0.142	1.600/0.063	0.700/0.028	1.000/0.039	0.950/0.037	1.900/0.075

**Suggested Pad Layout (Cont.)**

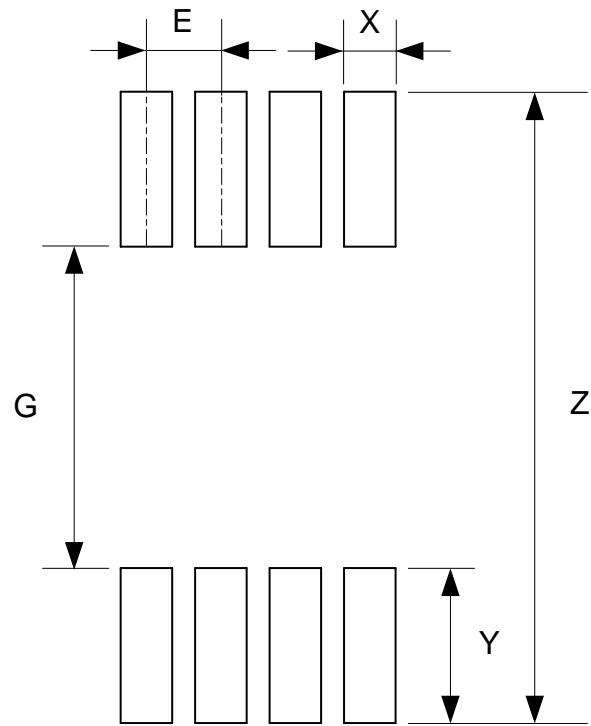
(2) Package Type: SOIC-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	6.900/0.272	3.900/0.154	0.650/0.026	1.500/0.059	1.270/0.050

**Suggested Pad Layout (Cont.)**

(3) Package Type: MSOP-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	5.500/0.217	2.800/0.110	0.450/0.018	1.350/0.053	0.650/0.026

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